



**FEATURES**

- TO-8 hermetic package
- Optimized die size for maximum signal
- Low capacitance



**ELECTRO-OPTICAL CHARACTERISTICS AT 25°C**

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Active Area	9.91mm x 4.28mm		42		mm <sup>2</sup>
Responsivity, $\mathcal{R}$	@ 632nm	0.35	0.40		A/W
Dark Current, $I_{dr}$	$V_R = 10V$		11	25	nA
Reverse Breakdown Voltage, $V_R$	$I_R = 10A$	25	60		Volts
Capacitance, C	$V_R = 10V$		85		pF
Rise Time	$V_R = 10V$		30		nsec
Series Resistance	$V_f = 1V$		35	100	Ohms

**THERMAL PARAMETERS**

Storage and Operating Temperature Range	-55°C TO 100°C
Maximum Junction Temperature	100°C
Lead Soldering Temperature <sup>1</sup>	260°

<sup>1</sup>1/16" from case for 10 seconds.

